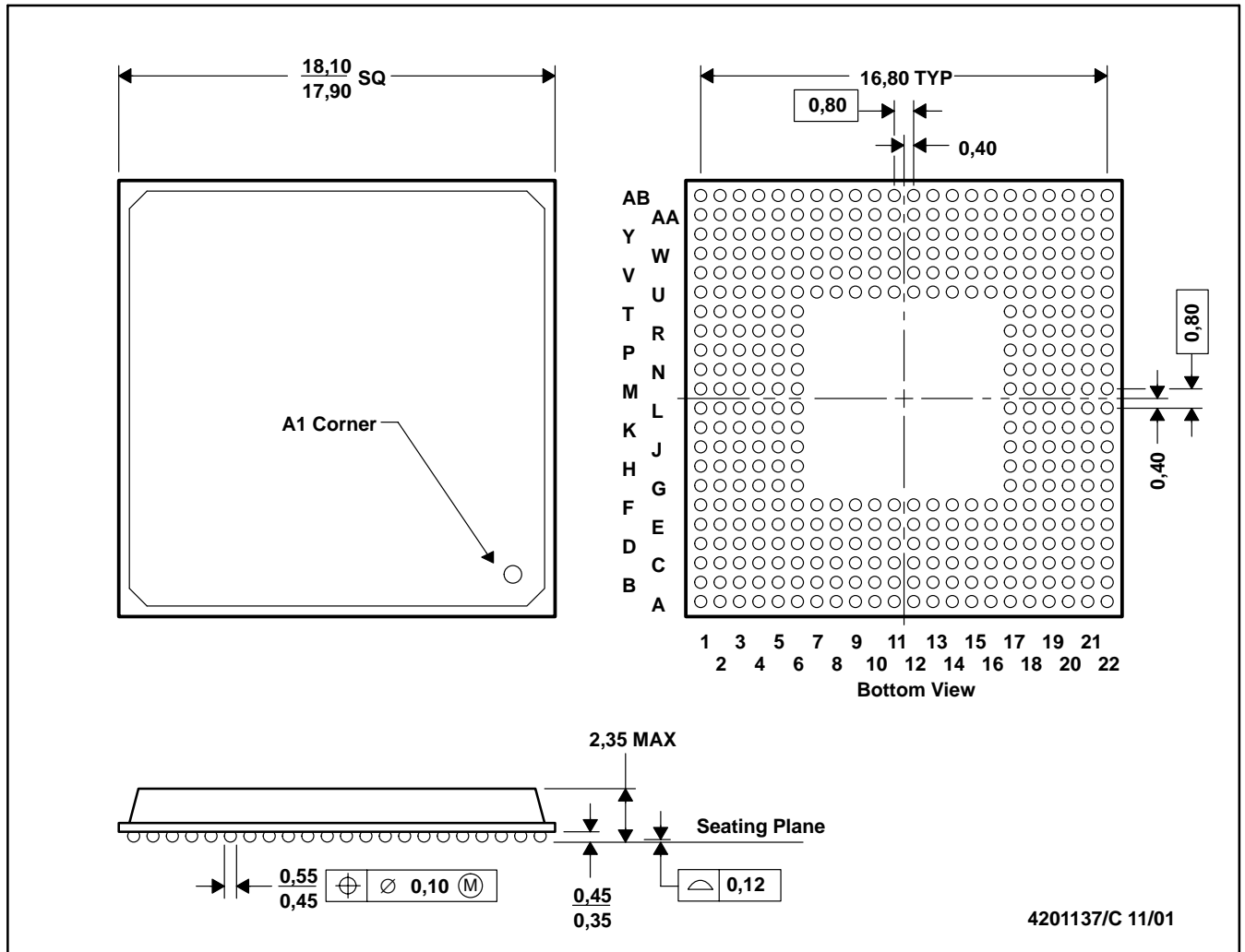


GNY (S-PBGA-N384)

PLASTIC BALL GRID ARRAY



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Flip chip application only
 D. Substrate color may vary

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